Application/Control Number: 10/630,427

Art Unit: 2813

## **DETAILED ACTION**

## **EXAMINER'S AMENDMENT**

An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

The application has been amended as follows:

abovelinel

At page 1, line 2, before the Technical Field section, insert:

RELATED PATENT DATA

This patent is a divisional application of U.S. Patent Application Serial No. 10/277,500, filed August 22, 2002 entitled "Semiconductor Processing Methods of Forming Conductive Lines," which is a Divisional Application of U.S. Patent Application Serial No. 09/848,825, filed May 3, 2001, entitled "Semiconductor Processing Methods of Forming integrated Circuitry, Forming Conductive Lines, Forming a Conductive Grid, Forming a Conductive Network, Forming an Electrical Interconnection to a Node Location, Forming an Electrical interconnection with a Transistor Source/Drain Region, and Integrated Circuitry," now US Patent No. 6589851, which is a Continuation Application of U.S. Patent Application Serial No. 09/310,044, filed May 11, 1999, now U.S. Patent No. 6,344,399 B1, which is a divisional application of U.S. Patent Application Serial No. 08/846,110, filed April 25, 1997, now U.S. Patent No. 6,004,835, the disclosure of which are hereby incorporated herein by reference.

